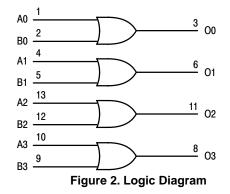
V <sub>CC</sub>	A2 13	B2	02	A3 10	B3 9	03 8
2						
1	2	3	4	5	6	7

Figure 1. Pinout: 14–Lead (Top View)

#### **PIN NAMES**

Pins	Function		
An, Bn	Data Inputs		
On	Outputs		



### **TRUTH TABLE**

Inputs		Outputs
An	An Bn On	
L	L	L
L	н	н
Н	L	н
Н	н	н

H = High Voltage Level L = Low Voltage Level

For I<sub>CC</sub> reasons, DO NOT FLOAT Inputs

#### MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	$-0.5 \le V_I \le +7.0$		V
Vo	DC Output Voltage	$-0.5 \leq V_O \leq V_{CC} + 0.5$	Output in HIGH or LOW State.(Note 1)	V
I <sub>IK</sub>	DC Input Diode Current	-50	V <sub>I</sub> < GND	mA
I <sub>OK</sub>	DC Output Diode Current	-50	V <sub>O</sub> < GND	mA
		+50	V <sub>O</sub> > V <sub>CC</sub>	mA
I <sub>O</sub>	DC Output Source/Sink Current	±50		mA
I <sub>CC</sub>	DC Supply Current Per Supply Pin	±100		mA
I <sub>GND</sub>	DC Ground Current Per Ground Pin	±100		mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150		°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. I<sub>O</sub> absolute maximum rating must be observed.

### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter		Min	Туре	Max	Unit
V <sub>CC</sub>	Supply Voltage	Operating Data Retention Only	2.0 1.5	2.5, 3.3 2.5, 3.3	3.6 3.6	V
VI	Input Voltage		0		5.5	V
Vo	Output Voltage	(HIGH or LOW State) (3-State)	0		V <sub>CC</sub>	V
I <sub>OH</sub>	HIGH Level Output Current	$V_{CC} = 3.0 V - 3.6 V$ $V_{CC} = 2.7 V - 3.0 V$ $V_{CC} = 2.3 V - 2.7 V$			-24 -12 -8	mA
I <sub>OL</sub>	LOW Level Output Current	$V_{CC} = 3.0 V - 3.6 V$ $V_{CC} = 2.7 V - 3.0 V$ $V_{CC} = 2.3 V - 2.7 V$			+24 +12 +8	mA
T <sub>A</sub>	Operating Free–Air Temperature		-40		+85	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate	, V <sub>IN</sub> from 0.8 V to 2.0 V, V <sub>CC</sub> = 3.0 V	0		10	ns/V

## DC ELECTRICAL CHARACTERISTICS

			T <sub>A</sub> = −40°C			
Symbol	Characteristic	Condition	Min	Max	Unit	
V <sub>IH</sub>	HIGH Level Input Voltage (Note 1.)	$2.3 \text{ V} \leq \text{V}_{CC} \leq 2.7 \text{ V}$	1.7		V	
		$2.7 \text{ V} \leq \text{V}_{CC} \leq 3.6 \text{ V}$	2.0			
V <sub>IL</sub>	LOW Level Input Voltage (Note 1.)	$2.3 \text{ V} \leq \text{V}_{CC} \leq 2.7 \text{ V}$		0.7	V	
		$2.7 \text{ V} \leq \text{V}_{CC} \leq 3.6 \text{ V}$		0.8		
V <sub>OH</sub>	HIGH Level Output Voltage	$2.3 \text{ V} \leq \text{V}_{CC} \leq 3.6 \text{ V}; \text{ I}_{OH} = -100 \ \mu\text{A}$	V <sub>CC</sub> – 0.2		V	
		$V_{CC} = 2.3 \text{ V}; I_{OH} = -8 \text{ mA}$	1.8			
		$V_{CC} = 2.7 \text{ V}; \text{ I}_{OH} = -12 \text{ mA}$	2.2			
		V <sub>CC</sub> = 3.0 V; I <sub>OH</sub> = -18 mA	2.4			
		V <sub>CC</sub> = 3.0 V; I <sub>OH</sub> = -24 mA	2.2			
V <sub>OL</sub>	LOW Level Output Voltage	$2.3 \text{ V} \leq \text{V}_{CC} \leq 3.6 \text{ V}; \text{ I}_{OL} = 100 \mu\text{A}$		0.2	V	
		V <sub>CC</sub> = 2.3 V; I <sub>OL</sub> = 8 mA		0.6		
		V <sub>CC</sub> = 2.7 V; I <sub>OL</sub> = 12 mA		0.4		
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 16 mA		0.4		
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 24 mA		0.55		
I <sub>I</sub>	Input Leakage Current	$2.3 \text{ V} \leq \text{V}_{CC} \leq 3.6 \text{ V}; 0 \text{ V} \leq \text{V}_{I} \leq 5.5 \text{ V}$		±5	μΑ	
I <sub>CC</sub>	Quiescent Supply Current	$2.3 \leq V_{CC} \leq 3.6$ V; V_I = GND or V_{CC}		10	μΑ	
		$2.3 \leq V_{CC} \leq 3.6$ V; $3.6 \leq V_{I} \text{ or } V_{O} \leq 5.5$ V		±10		
$\Delta I_{CC}$	Increase in I <sub>CC</sub> per Input	$2.3 \le V_{CC} \le 3.6 \text{ V}; \text{ V}_{IH} = V_{CC} - 0.6 \text{ V}$		500	μΑ	

1. These values of  $V_I$  are used to test DC electrical characteristics only.

#### AC CHARACTERISTICS $t_R = t_F = 2.5 \text{ ns}; R_L = 500 \Omega$

				Limits					
				T <sub>A</sub> = −40°C to +85°C					
			$V_{CC}$ = 3.3 V $\pm$ 0.3 V		V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> = 2.5	$V \pm 0.2 V$	
			C <sub>L</sub> = 50 pF		C <sub>L</sub> = 50 pF		C <sub>L</sub> = 30 pF		
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Unit
t <sub>PLH</sub>	Propagation Delay Time	1	1.5	5.5	1.5	6.2	1.5	6.6	ns
t <sub>PHL</sub>	Input to Output		1.5	5.5	1.5	6.2	1.5	6.6	
t <sub>OSHL</sub>	Output-to-Output Skew			1.0					ns
t <sub>OSLH</sub>	(Note 2)			1.0					

 Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

#### **DYNAMIC SWITCHING CHARACTERISTICS**

			T <sub>A</sub> = +25°C			
Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V <sub>OLP</sub>	Dynamic LOW Peak Voltage	$V_{CC}$ = 3.3 V, $C_L$ = 50 pF, $V_{IH}$ = 3.3 V, $V_{IL}$ = 0 V		0.8		V
	(Note 3)	$V_{CC}$ = 2.5 V, $C_L$ = 30 pF, $V_{IH}$ = 2.5 V, $V_{IL}$ = 0 V		0.6		V
V <sub>OLV</sub>	Dynamic LOW Valley Voltage	$V_{CC}$ = 3.3 V, $C_L$ = 50 pF, $V_{IH}$ = 3.3 V, $V_{IL}$ = 0 V		-0.8		V
	(Note 3)	$V_{CC}$ = 2.5 V, $C_L$ = 30 pF, $V_{IH}$ = 2.5 V, $V_{IL}$ = 0 V		-0.6		V

 Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

### **CAPACITIVE CHARACTERISTICS**

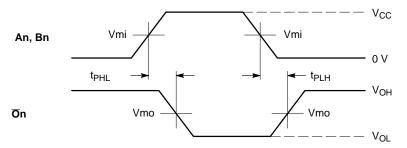
Symbol	Parameter	Parameter Condition		
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	7	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	8	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, $V_{CC}$ = 3.3 V, $V_I$ = 0 V or $V_{CC}$	25	pF

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC74LCX32D	SOIC-14	55 Units / Rail
MC74LCX32DR2	SOIC-14	2500 Tape & Reel
MC74LCX32DR2G	SOIC-14 (Pb-Free)	2500 Tape & Reel
MC74LCX32DT	TSSOP-14*	96 Units / Rail
MC74LCX32DTG	TSSOP-14*	96 Units / Rail
MC74LCX32DTR2	TSSOP-14*	2500 Tape & Reel
MC74LCX32DTR2G	TSSOP-14*	2500 Tape & Reel
MC74LCX32MEL	SOEIAJ-14	2000 Tape & Reel
MC74LCX32MELG	SOEIAJ-14 (Pb-Free)	2000 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*This package is inherently Pb-Free.

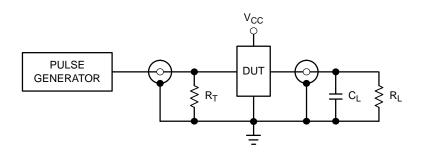


WAVEFORM 1 - PROPAGATION DELAYS

 $t_R = t_F = 2.5$  ns, 10% to 90%; f = 1 MHz;  $t_W = 500$  ns

	Vcc				
Symbol	3.3 V <u>+</u> 0.3 V	2.7 V	2.5 V <u>+</u> 0.2 V		
Vmi	1.5 V	1.5 V	Vcc/2		
Vmo	1.5 V	1.5 V	Vcc/2		

Figure 3. AC Waveforms

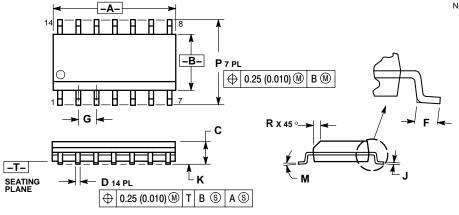


 $\begin{array}{l} C_L = 50 \ \text{pF} \ \text{at} \ V_{CC} = 3.3 \pm 0.3 \ \text{V} \ \text{or equivalent} \ (\text{includes jig and probe capacitance}) \\ C_L = 30 \ \text{pF} \ \text{at} \ V_{CC} = 2.5 \pm 0.2 \ \text{V} \ \text{or equivalent} \ (\text{includes jig and probe capacitance}) \\ R_L = \ R_1 = 500 \ \Omega \ \text{or equivalent} \\ R_T = \ Z_{OUT} \ \text{of pulse generator} \ (\text{typically 50 } \Omega) \end{array}$ 

Figure 4. Test Circuit

### PACKAGE DIMENSIONS

SOIC-14 **D SUFFIX** CASE 751A-03 **ISSUE G** 



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.

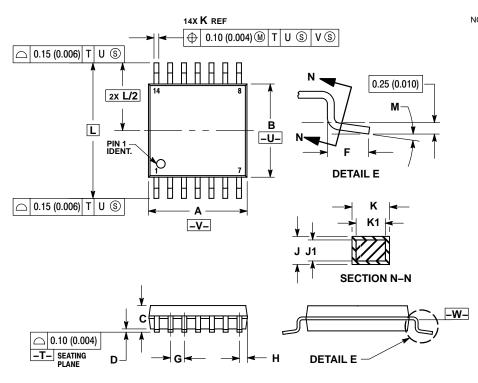
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

PER SIDE. 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050 BSC	
J	0.19	0.25	0.008	0.009
Κ	0.10	0.25	0.004	0.009
м	0 °	7 °	0 °	7 °
Ρ	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

TSSOP-14 DT SUFFIX CASE 948G-01 **ISSUE A** 



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.

2. DIMENSION A DOES NOT INCLUE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT

EXCEED 0.15 (0.006) PER SIDE. 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL

NOT EXCEED 0.25 (0.010) PER SIDE. 5. DIMENSION K DOES NOT INCLUDE 5. DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08

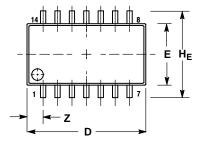
(0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. 6. TERMINAL NUMBERS ARE SHOWN FOR

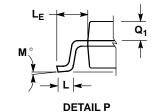
7. DIRENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–. 7.

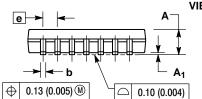
	MILLIN	IETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
н	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
Κ	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 °	8 °	0 °	8 °

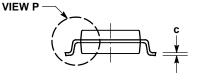
### PACKAGE DIMENSIONS

SOEIAJ-14 **M SUFFIX** CASE 965-01 **ISSUE O** 









NOTES:

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE. 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018). MILLIMETERS INCHES

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
Г	0.50	0.85	0.020	0.033
LΕ	1.10	1.50	0.043	0.059
Μ	0 °	10 °	0 °	10 °
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Ζ		1.42		0.056

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